

NOTES:

- MATERIAL:
HOUSING: LCP+30% G.F., UL 94V-0 RATED, COLOR BLACK.
CONTACTS: COPPER ALLOY.
SHIELD COVER: SUS304, 0.2T.
- PLATING:
CONTACT AREA: HARD GOLD PLATING OVER 1.27 μm(50 μ")MIN, NICKEL UNDERPLATING.
SOLDERING ZONE: 3.05 μm(120 μ")MIN. 100% TIN, OR LEAD-FREE PLATING PER PART NUMBER DESIGNATION, OVER NICKEL UNDERPLATING.
SHIELD COVER: GOLD FLASH NICKEL UNDERPLATING.
UNDERPLATING: 1.27 μm (50 μ")MIN. NICKEL ALLOVER.
- CUTTING BURR ALLOWED: 0.03mm MAX.
- COPLANARITY IS 0.10mm MAX.

ORDER INFORMATION

S I M C P 1 1 5 A - 1 8 0 6 G B B - U

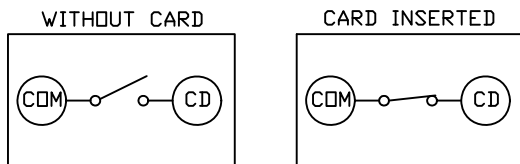
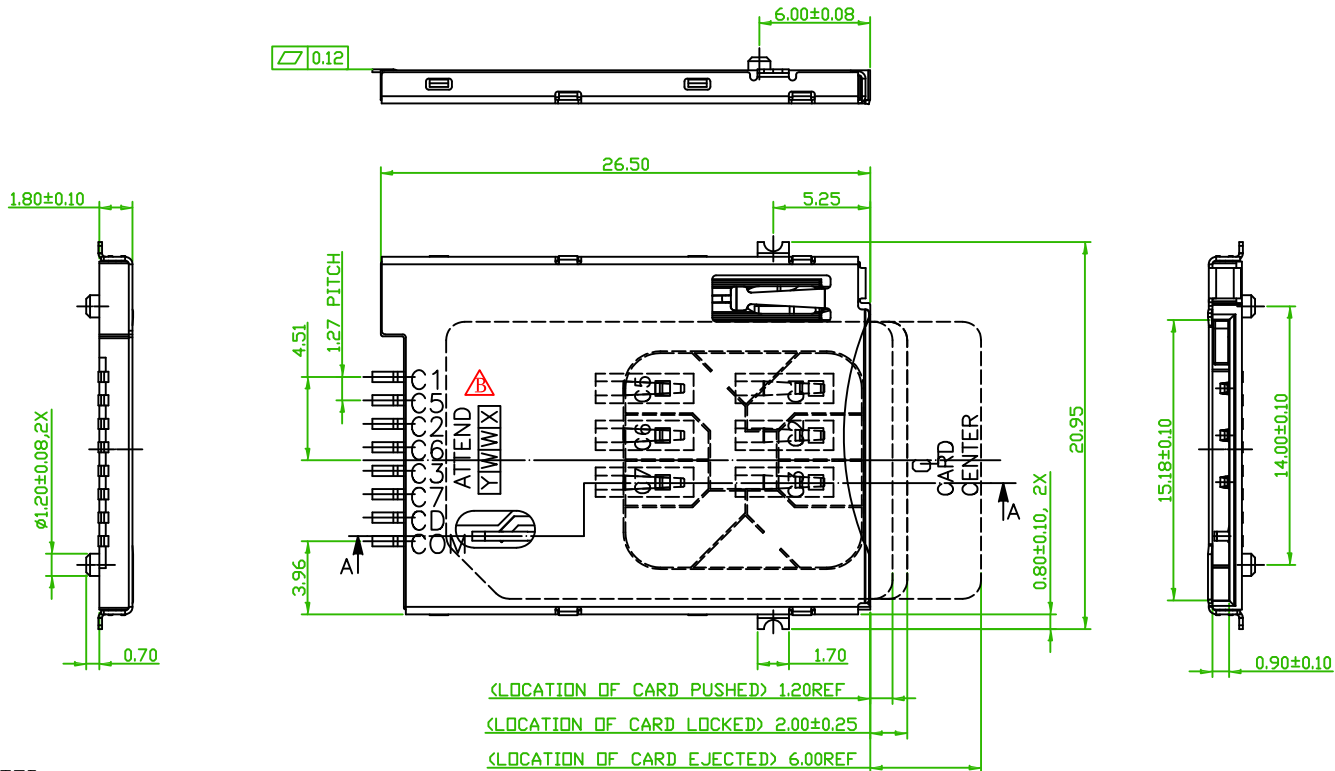
◎:Standard Recommend

20:Plastic Height H=2.0mm GB:Gold 10u" B:Black Insulator U:RoHS+LCP



PARTS LIST

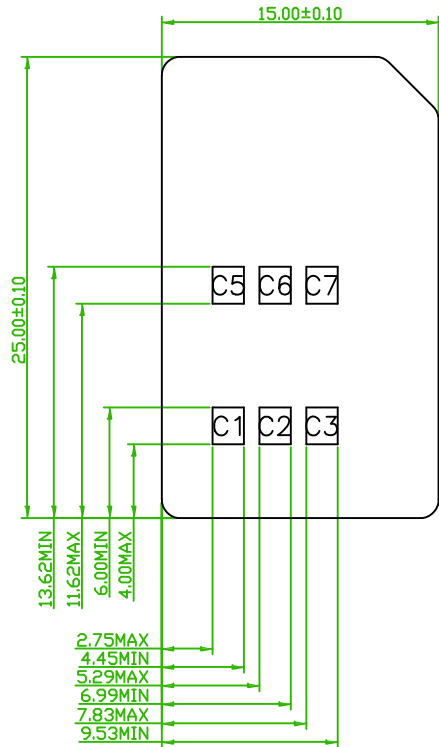
ITEM	DESCRIPTION	QTY(PC'S)
1	HOUSING	1
2	SLIDER	1
3	MAIN CONTACT	1
4	CDM CONTACT	1
5	CD CONTACT	1
6	METAL COVER	1
7	CRANK	1
8	SPRING	1



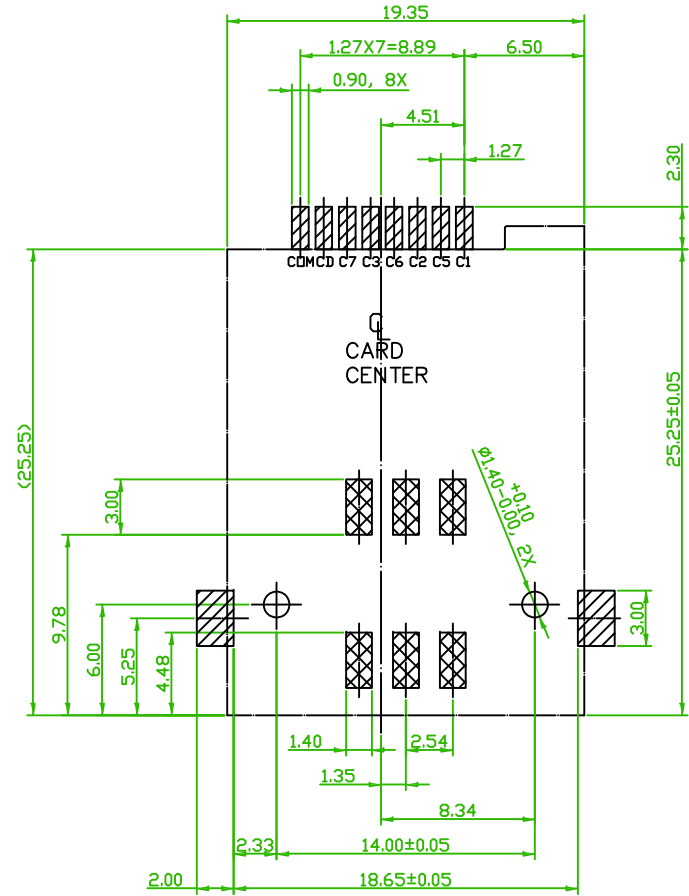
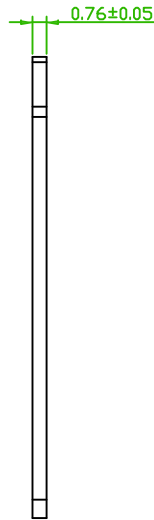
CARD DETECT SW. STATUS.

<p>Amtek Technology Co., Ltd. TEL:886-2-2260-6878 FAX:886-2-2260-6030</p>	品名 TITLE	SIM Card Push Push Type				
	品號 PART NO.	SIMCP115A-1806GBB-U			日期 DATE	2011/06/13
	圖號 DRAWING NO.	SIMCP115A-1806GBB-U	版本 REV.	B	繪圖 DRAWN	Joe
	客戶品號 CUSTOMER P/N		比例 SCALE	FREE	核對 CHECKED	Alvin
公差 TOLERANCE	.X ±0.25 .XX ±0.20	單位 UNIT	mm	核准 APPROVED	James	

△	B	Add the mark	2015/09/09
AREA	REV.	DESCRIPTION	DATE



APPLICABLE CARD SIZE



RECOMMENDED PCB LAYOUT

— TRACR PROHIBITION AREA

PIN DEFINITION						
NAME	C1	C2	C3	C5	C6	C7
TYPE	Vcc	RST	CLK	GND	Vpp	I/O

 糧德精密有限公司 Amtek Technology Co., Ltd. TEL: 886-2-2260-6878 FAX: 886-2-2260-6030	品名	SIM Card Push Push Type				
	TITLE					
	品號	SIMCP115A-1806GBB-U			日期	2011/06/13
	PART NO.				繪圖	Joe
	圖號	SIMCP115A-1806GBB-U	版本	B	核對	Alvin
	DRAWING NO.				核准	James
客戶品號				比例	FREE	
CUSTOMER P/N				SCALE	mm	
公差	.X ±0.25	單位	mm	核對	James	
TOLERANCE	.XX ±0.20	UNIT	mm	APPROVED		

AREA	REV.	DESCRIPTION	DATE
	B	Add the mark	2015/09/09
			Roy